

SEP 27 2004

S/N 10/786,354

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al. Examiner: Andy Huynh
Serial No.: 10/786,354 Group Art Unit: 2818
Filed: February 25, 2004 Docket: 303.686US3
Title: MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS
AND AIR GAPS

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

The present application is either a U.S. national patent application filed after June 30, 2003 or an international application that entered the national stage under 35 U.S.C. § 371 after June 30, 2003. Thus, Applicant believes that the U.S. Patent & Trademark Office has waived the requirement under 37 C.F.R. 1.98 (a)(2)(i) for submitting a copy of each cited U.S. patent and each U.S. patent application publication. The waiver is provided in a pre-OG notice from the U.S. Patent & Trademark Office entitled "Information Disclosure Statements May Be Filed

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Dkt: 303.686US3

Without Copies of U.S. Patents and Published Applications in Patent Applications filed after June 30, 2003" and dated July 11, 2003. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

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24 Sept '04

By

Timothy B Clise
Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 24th day of September, 2004.

Name

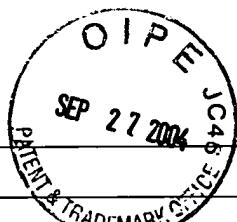
Amy Moriarty

Signature

Amy Moriarty

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(Use as many sheets as necessary)



Sheet 1 of 1

Complete if Known

Application Number	10/786,354
Filing Date	February 25, 2004
First Named Inventor	Ahn, Kie
Group Art Unit	2818
Examiner Name	Huynh, Andy

Attorney Docket No: 303.686US3

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-20010002333	05/31/2001	Huang, Chao-Yuan , et al.	438	637	03/29/1999
	US-1,254,987	01/29/1918	Cooper, H. S.			10/15/1917
	US-1,976,375	10/09/1934	Smith, J. K.	148	11.5	01/27/1931
	US20020109233	08/15/2002	Farrar, Paul A.	257	762	04/05/2002
	US-2,244,608	06/03/1941	Cooper, H. S.	75	138	02/09/1939
	US-2,842,438	07/08/1958	Saarivirta, M. J., et al.	75	153	08/02/1956
	US-3,147,110	09/01/1964	Foerster, G. S.	75	122.5	11/27/1961
	US-3,506,438	04/14/1970	Krock, R. H., et al.	75	208	07/24/1967
	US-3,548,948	12/22/1970	Richmond, W. J., et al.	164	68	01/23/1969
	US-3,687,737	08/29/1972	Krock, R. H., et al.	148	2	07/17/1970
	US-3,923,500	12/02/1975	Kitazawa, Kunio , et al.	75	156.5	09/04/1974
	US-4,213,818	07/22/1980	Lemons, Kyle E., et al.	438	719	01/04/1979
	US-5,668,398	09/16/1997	Havemann, R. H., et al.	257	522	04/12/1996
	US-6,197,181	03/06/2001	Chen, Linlin	205	123	03/20/1998
	US-6,268,277	07/31/2001	Bang, D	438	619	07/16/1999
	US-6,448,331	09/10/2002	Ioka, T. , et al.	524	859	11/12/1999

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
	EP-0304046	02/22/1989	Fujimura, S. , et al.	G03F	7/26	
	JP-05267643 ^{With English Abstract}	10/15/1993	Muraoka, Toru	029	46	
	JP-07-321111 ^{With English Abstracts}	08/12/1995	Tetsuo, K.	H01L	21/320 5	
	JP-07078815 ^{With English Abstracts (Derrived EPO)}	03/20/1995	Miyamoto, I.	HO1 L	21/320 5	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		"Brooks Model 5964 High Performance Metal Seal Mass Flow Controller (Introduced in 1991)", <u>Brooks Instrument</u> , http://www.frc.com/brooks/semiconductor/products1i.html , (1991), 1 page	

EXAMINER

DATE CONSIDERED